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(54) HIGHLY PURIFIED TITANIUM MATERIAL, METHOD FOR PREPARATION OF IT AND SPUTTERING TARGET USING IT

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patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

This patent is subject to a terminal disclaimer.

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Related U.S. Application Data

(62) Division of application No. 08/592,237, filed on Jan. 26, 1996, now abandoned, which is a continuation of application No. 08/028,084, filed on Mar. 8, 1993, now Pat. No. 5,584, 906, which is a division of application No. 07/924,770, filed on Apr. 9, 1992, now Pat. No. 5,204,057, which is a continuation of application No. 07/550,682, filed on Jul. 10, 1990, now abandoned.

(30) Foreign Application Priority Data

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		H01L 29/40
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- (56) References Cited

U.S. PATENT DOCUMENTS

3,137,641 A	6/1964	Slatin	204/64 T
3,891,456 A	6/1975	Hohman et al	134/3

(List continued on next page.)

FOREIGN PATENT DOCUMENTS

DE 2 623 740 12/1976 EP 0 248 338 12/1987

(List continued on next page.)

OTHER PUBLICATIONS

Nauchn. Tr. Naucho-Issled. Proektn. Inst. Redkomet. Prom-st. "The Behaviour of Impurities in the Production of High Purity Titanium by Iodide Refining", pp. 1–6, (1981). Metals & Technology, "The Role of Pure Metals", vol. 55, No. 9, Sep. (1995).

American Metal Market, "MRC Develops 99.9999% Pure Titanium For Thin Film and Aerospace Devices", Mar. 3, (1964).

(List continued on next page.)

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(57) ABSTRACT

The crude Ti particles prepared by molten salt electrolysis or Iodide method are classified into each particle diameter according to contents of impurities, and the crude Ti particles having a desired particle diameter are selected from the crude Ti particles classified depending on each particle diameter. Otherwise, the crude Ti particles are acid-treated. Then they are electron-beam-melted. Through the above production process, there is prepared a highly purified Ti material having an oxygen content of not more than 350 ppm, Fe, Ni and Cr contents of not more than 15 ppm each, Na and K contents of not more than 0.5 ppm each, a reduction of area as a material characteristic of not less than 70%, and a thermal conductivity of not less than 16 W/m K. In short, the highly purified Ti material satisfying high purity, good processability and good thermal conductivity can be obtained. A film having more uniform thickness of film and inside structure can be obtained from a sputtering target prepared using the above highly purified Ti material.

14 Claims, 3 Drawing Sheets

